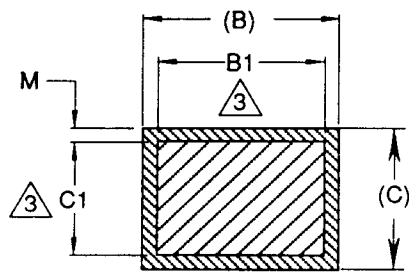
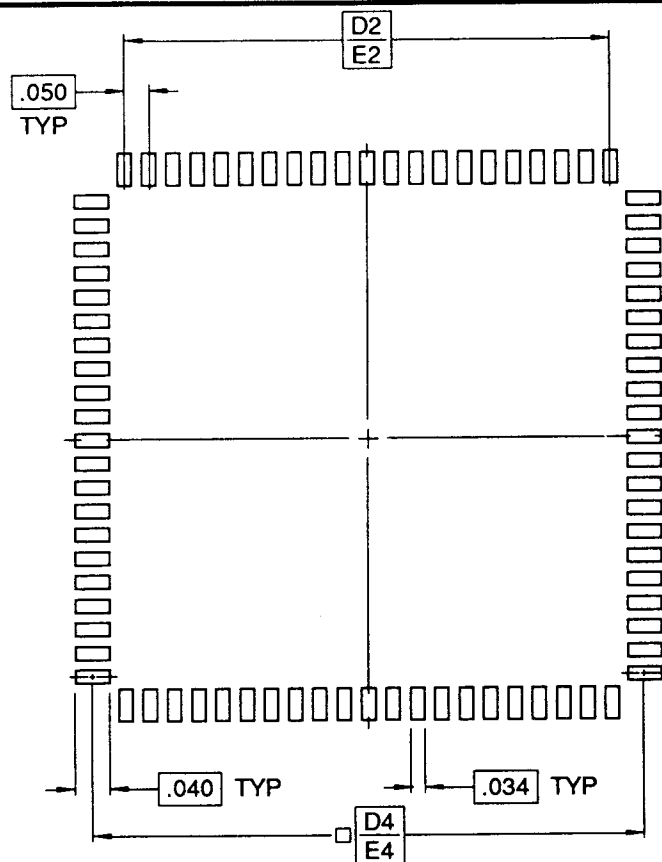


DETAIL A



SECTION B-B



### LEAD POSITION OVERLAY

#### NOTES:

1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M-1982.
2. LEAD POSITION DETERMINED BY OVERLAY SHOWN ON SHEET 2. THE ENTIRE SEATING PLANE OF EVERY LEAD MUST SIMULTANEOUSLY RESIDE WITHIN DEFINED AREA OF THE OVERLAY WHEN VIEWED FROM THE BOTTOM.
3. DIMENSIONS B1 AND C1 APPLY TO BASE METAL ONLY. DIMENSION M APPLIES TO PLATING THICKNESS.
4. A PIN ONE IDENTIFICATION MARK SHALL BE LOCATED ADJACENT TO THE INDEX CORNER AND WITHIN THE SHADED AREA SHOWN.
5. CONTROLLING DIMENSION: INCH.
6. SYMBOL N IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS.
7. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL. BUT ANY INDEX SHALL BE PER JEDEC PUBLICATION 95 LEADLESS CHIP CARRIER INDEXING.
8. THE MAXIMUM "A" DIMENSION ALLOWS FOR AN EPROM WINDOW LID.

SYMBOL	VARIATIONS												ALL DIMENSIONS IN INCHES					
	AA			NOTE	AB			NOTE	AC			NOTE	AD			NOTE		
	MIN	NOM	MAX		MIN	NOM	MAX		MIN	NOM	MAX		MIN	NOM	MAX			
A	.115	.125	.190	8	.115	.125	.190	8	.115	.125	.190	8	.115	.125	.190	8		
A1	—	.060	—	3	—	.065	—	3	—	.065	—	3	—	.080	—	3		
B	.013	—	.023		.013	—	.023		.013	—	.023		.013	—	.023			
B1	.013	—	.020		.013	—	.020		.013	—	.020		.013	—	.020			
B2	.022	—	.035		.022	—	.035		.022	—	.035		.022	—	.035			
C	.007	—	.013	3	.007	—	.013	3	.007	—	.013	3	.007	—	.013	3		
C1	.007	—	.010		.007	—	.010		.007	—	.010		.007	—	.010			
D/E	.475	.490	.500		.675	.690	.700		.775	.790	.800		.975	.990	1.000			
D1/E1	.420	—	.460		.620	—	.660		.720	—	.760		.920	—	.960			
D2/E2	.300 BSC			3	.500 BSC			3	.600 BSC			3	.800 BSC			3		
D4/E4	.430 BSC				.630 BSC				.730 BSC				.930 BSC					
L	.005	—	—	3	.005	—	—	3	.005	—	—	3	.005	—	—	3		
L1	.020	—	—		.020	—	—		.020	—	—		.020	—	—			
L2	.025	—	—		.025	—	—		.025	—	—		.025	—	—			
Q	.003	—	—		.003	—	—		.003	—	—		.003	—	—			
M	—	—	.0015		—	—	.0015		—	—	.0015		—	—	.0015			
R	.020	—	.040		.020	—	.040		.020	—	.040		.020	—	.040			
N	28		6	44		6	52		6	68		6						

NOTE 1, 5

	AE			NOTE
	MIN	NOM	MAX	
A	.115	.160	.190	8
A1	—	.080	—	
B	.013	—	.023	
B1	.013	—	.020	3
B2	.022	—	.035	
C	.007	—	.013	
C1	.007	—	.010	3
D/E	1.175	1.190	1.200	
D1/E1	1.120	—	1.165	
D2/E2	1.000 BSC			
D4/E4	1.130 BSC			
L	.005	—	—	
L1	.020	—	—	
L2	.025	—	—	
Q	.003	—	—	
M	—	—	.0015	3
R	.020	—	.040	
N		84		6

NOTE 1, 5

REF. 10-284

ISSUE A

JEDEC SOLID STATE PRODUCT OUTLINES	Ceramic Multilayer Leaded Chip Carrier, .050" pitch, J-Bend	ISSUE A	DATE 5/90	MO-107	SHEET 3 of 3
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